



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE8458G		<b>Issued</b>		28. August 2013		
<b>MA#</b>		MA000977770						
<b>Package</b>		PG-DSO-8-16		<b>Weight*</b>		83.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.909	4.68	4.68	46750	46750
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8578	
wire	non noble metal	copper	7440-50-8	29.121	34.83	35.74	348317	357431
	noble metal	gold	7440-57-5	0.121	0.14	0.14	1445	1445
	encapsulation	organic material	carbon black	1333-86-4	0.093	0.11		1114
plastics	plastics	epoxy resin	-	4.285	5.13		51254	
		silicondioxide	60676-86-0	42.199	50.48	55.72	504745	557113
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9734	9734
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7778	7778
glue	plastics	acrylic resin	-	0.363	0.43		4345	
		silver	7440-22-4	1.288	1.54	1.97	15404	19749
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com